

Article

An Improved Understanding of Chalcopyrite Leaching Mechanisms: The Influence of Anisotropic Crystal Planes

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Abstract: Chalcopyrite (CuFeS₂) particles, exposing anisotropic crystal planes during the grinding process, possess comprehensive surface properties that affect their leaching behaviors. In order to investigate the influence of anisotropic crystal planes on the leaching mechanisms, CuFeS₂ particles with anisotropic crystal planes were produced by employing three-head laboratory grinder mill (TM), rod mill (RM), and ball mill (BM) and were then leached in a sulfuric acid solution at pH = 1. Based on the XRD, SEM, XPS, and simulation results, (112), (102), (312), (110), (116), (100), and (001) planes were mainly exposed on the CuFeS₂ surface during the crushing and grinding process. In addition, fewer (112), (102), (312), and (110) planes but more (116), (100), and (001) planes were exposed on the CuFeS₂ samples in the TM method than in the RM and BM methods. Since the leaching rates were in the order of (001) > (100) > (116) > (110) > (312) > (102) > (112) planes, the Cu extractions followed an order of TM > RM > BM. This study, therefore, provides an excellent theoretical basis for the effect of anisotropic crystal planes on CuFeS₂ leaching, further improving the understanding of CuFeS₂ leaching mechanisms.

Keywords: chalcopyrite; leaching; anisotropic crystal planes; density functional theory; mechanisms



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1. Introduction

Copper is an important nonferrous metal that has been widely used in various areas such as the light, electrical, communications, construction, and machinery manufacturing industries and other industries [1]. Copper metal is mainly purified from chalcopyrite (CuFeS₂), since approximately 70% of the Earth's copper resources are found as CuFeS₂ [2,3]. The average copper grades are about 0.4% and 1~2% for open-cast and underground CuFeS₂ deposits [1], respectively. Generally, a flotation process is employed to obtain a CuFeS₂ concentrate [4], followed by the metallurgy process for copper production [5]. In addition, pyrometallurgical methods are preferentially considered for high-grade CuFeS₂ concentrates (greater than 20%) [6]. However, these methods lead to extensive environmental problems due to the emission of SO₂ [7,8]. As an alternative to pyrometallurgy, hydrometallurgy has been paid much attention due to its advantages, such as being a more economical method of treating low-grade ores and being more environmentally friendly [3,5].

However, hydrometallurgical processing of CuFeS₂ has not been widely adopted in the industry due to the extremely slow leaching kinetics [9–14], mainly due to the formation of passivation layers on the CuFeS₂ surface [15–21]. Thus, the investigation of the formation and elimination mechanisms of the passivation layer is very important for the application of CuFeS₂ hydrometallurgy. In recent years, various analytical methods have been applied to investigate the properties of the passivating layer on the CuFeS₂ surface [22–25], such as scanning electron microscopy (SEM), synchrotron scanning photoelectron microscopy (SPEM), transmission electron microscopy (TEM), and X-ray photoelectron spectroscopy

(XPS). However, there is no generally accepted theory as to the composition of the passivation layer. Córdoba et al. [3] reported that the passivation layers were predominantly composed of bimetallic sulfide, iron-deficient copper polysulfide, and elemental sulfide. Li et al. [5] reported that the formation of elemental sulfide, disulfide, polysulfide, and iron hydroxy-oxide inhibited the leaching of CuFeS_2 . In this case, it is extremely urgent to clarify the surface properties of CuFeS_2 to better understand the leaching mechanisms.

In addition, the surface properties of minerals are closely associated with the mineral's exposed planes. For instance, Wei et al. [26] indicated that the MoS_2 face (i.e., (001) plane) exhibited hydrophobic properties while the MoS_2 edges (i.e., (103), (105), (100), and (110) planes) exhibited hydrophilic properties. Therefore, investigations on the anisotropic crystal planes are very important for determining the surface properties of CuFeS_2 . Normally, the CuFeS_2 (112), (102), (312), (110), (116), (100), and (001) planes are exposed during the crushing and grinding process [27–30]. The properties of these crystal planes have been widely investigated using density functional theory (DFT) calculations from the viewpoint of theory. For example, de Oliveira et al. [31] reported three different reconstruction mechanisms for CuFeS_2 -typical planes, wherein the reconstructed planes presented different properties. Wei et al. [27] investigated the relaxation and oxidation of the CuFeS_2 (001) and (112) planes on exposure to O_2 and H_2O , indicating that the formation of disulfide (S_2^{2-}) on the CuFeS_2 (001) plane and polysulfide (S_n^{2-}) on the CuFeS_2 (112) plane inhibited the leaching process. Meanwhile, the CuFeS_2 (001) plane per unit area was more easily oxidized than the (112) plane. However, the influence of the anisotropic crystal planes' properties on the actual leaching performance of CuFeS_2 and the underlying mechanisms remain unclear up to now.

In this study, three different grinding methods (i.e., a three-head laboratory mill with a grinder mill (TM), a rod mill (RM), and a ball mill (BM)) were considered to obtain CuFeS_2 particles with anisotropic crystal planes, followed by the leaching experiment to investigate the influence of the anisotropic crystal plane on the leaching behavior of CuFeS_2 . The anisotropy of the CuFeS_2 raw samples was analyzed using X-ray diffraction (XRD) and SEM; XPS and DFT simulation were employed to investigate the anisotropic oxidation properties of the CuFeS_2 planes. This study, therefore, provides an excellent theoretical basis in revealing the influence of anisotropic crystal planes on CuFeS_2 leaching mechanisms, providing new insights for the application of CuFeS_2 hydrometallurgy.

2. Materials and Methodology

2.1. CuFeS_2 Samples

The high-purity chunks of CuFeS_2 samples (Figure S1 and Table S1, Supplementary Materials, the content of CuFeS_2 was nearly 98 wt%) obtained from the Araci Mine in Peru were crushed to small particles (around 5 mm) and milled in three ways, i.e., TM (RK/XPM 120 × 3 three-head grinding machine, Wuhan Rock Grinding Equipment Manufacturing Co., Ltd., Wuhan, China), RM (XMB-70, three-roller, four-barrel rod mill, Wuhan Prospecting Machinery Factory, Wuhan, China), and BM (XMB-70, three-roller, four-barrel ball mill, grinding mediums using ceramic balls), followed by wet sieving to obtain particles with two size fractions of 38–75 μm and 75–150 μm . These samples were treated using ultrasonication (JP-020, Shenzhen Jie Meng Cleaning Equipment Co., Ltd, Shenzhen China) under ethanol solution conditions at 40 KHz for 2 mins to remove the attached fine particles from the sample surfaces, which were freeze-dried (LGJ-12, vacuum freeze dryer, Beijing Songyuanhuaxing Technology Develop Co., Ltd., Beijing, China) to avoid further surface oxidation.

2.2. Leaching Experiments

Briefly, 500 mL glass reactor vessels with a 5-port lid were used for the leaching experiments. A 1 g CuFeS_2 sample and 400 mL of a sulfuric acid solution at pH = 1 were poured into the reactor vessel to avoid interference from other ions [5] and were then heated using a thermostatically controlled silicone oil bath at 75 °C. The 5-port lid provided access

to the leach solution; three ports were used to house a thermometer, a Teflon impeller, and a reflux condenser, and the remaining two ports were covered with a plug to avoid moisture evaporation. The four-blade Teflon impeller was driven by a digitally controlled stirrer at a constant agitation speed of 170 rpm.

Subsequently, 5 mL solution samples were taken twice a day at intervals of 8 h and 16 h, respectively. Then, the solution was filtered through a 0.22 μm membrane for pH and Cu-concentration tests. The pH was maintained at 1 by adding 5 M H_2SO_4 [5].

2.3. Bulk and Surface Analyses

In order to determine the exposed crystal planes for the CuFeS_2 samples treated through the TM, RM and BM methods, CuFeS_2 samples with size fractions of 38–75 μm and 75–150 μm were directly tested using XRD (D8 Advance, Bruker, Germany, with 2θ from 10° to 70° ($\text{Cu K}\alpha$) at a scanning speed of $0.2^\circ/\text{min}$). The obtained data were analyzed using Jade 6.0 software (Materials Data, Inc., Livermore, CA, USA) to determine the exposed crystal planes corresponding to each diffraction peak based on the standard XRD pattern. Since the preferred orientation may exist in the XRD test for bigger CuFeS_2 particles, side-loading methods and the rotation of the sample table were considered to avoid the preferred orientation [32]. SEM analyses (Zeiss Ultra Plus, Oberkochen, Germany) were conducted on the surface of leached CuFeS_2 , with an acceleration voltage of 30 keV.

A Thermo Scientific K-Alpha (Thermo Fisher-VG Scientific, Waltham, MA, USA) was used for XPS analyses of the leached CuFeS_2 . The XPS instrument was operated using an Al K-Alpha X-ray source ($h\nu = 1486.6$ eV) at 12 kV and 6 mA with a pressure of 2.0×10^{-7} m Bar. Next, 2.0 g of samples with a particle size of 38–75 μm were conditioned. The obtained spectra were analyzed using Avantage software (Thermo Fisher-VG Scientific, Thermo Fisher Scientific, Waltham, MA, USA). The binding energies were referenced to the C 1s peak at 284.8 eV.

2.4. DFT Calculation

The CuFeS_2 bulk was constructed through Materials Studio 8.0 according to our previous research [27]. The geometric optimization calculation was performed using the same calculation parameters, i.e., generalized gradient approximation (GGA) with PW91 corrections in the CASTEP package, with a cutoff energy of 351 eV, and a Monkhorst–Pack scheme with a $3 \times 3 \times 3$ k -point mesh. Subsequently, the CuFeS_2 (112), (102), (312), (110), (116), (100), and (001) planes were cleaved based on the optimized CuFeS_2 bulk. The surface energies (E_s) [27,33] and the adsorption energy [34] were calculated to determine the reactivity of the CuFeS_2 plane.

3. Results and Discussion

3.1. Anisotropic Leaching Results

In order to investigate the influence of the anisotropic crystal plane on CuFeS_2 leaching, three different grinding methods (TM, RM, and BM) were employed to obtain CuFeS_2 particles with anisotropic crystal planes, which were then leached in a H_2SO_4 solution. For the three CuFeS_2 samples with a particle size of 38–75 μm , a similar increasing trend of Cu extractions was obtained (Figure 1a), giving Cu extractions at around 76.2%, 78.9%, and 87.5% at 648 h for the TM, RM, and BM methods, respectively. In contrast, significantly different evolutions of Cu extractions were observed for the three CuFeS_2 samples with a particle size of 75–150 μm (Figure 1b), giving a Cu extraction order of $\text{TM} > \text{RM} > \text{BM}$. It should be noted that Cu was nearly completely extracted within 500 h for the TM method, while the Cu extractions were around 94% and 53% at 648 h for the RM and BM methods, suggesting that the TM method was beneficial for the leaching of bigger CuFeS_2 particles.

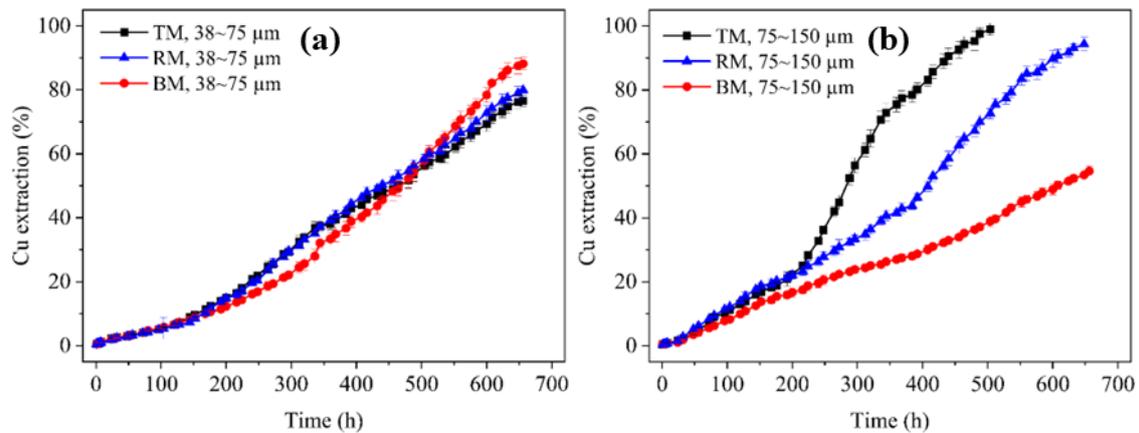


Figure 1. Leaching experiment results of CuFeS_2 samples obtained through three grinding methods: (a) 38~75 μm ; (b) 75~150 μm .

In addition, the leaching rate was higher for smaller CuFeS_2 particles in the BM method due to their bigger surface area [5,35]. However, the bigger CuFeS_2 particles obtained through the TM and RM methods exhibited a higher leaching rate than the smaller particles, especially for the TM method, suggesting that the surface properties of the CuFeS_2 particles in the three grinding methods led to significantly different leaching results.

3.2. Anisotropy of CuFeS_2 Raw Samples

In order to investigate the differences in the surface properties, XRD and SEM tests were employed for the CuFeS_2 raw samples. Figure 2 shows the XRD patterns; the typical exposed planes for all the CuFeS_2 raw samples were the (112), (102), (312), (110), (116), (100), and (001) planes [27–30]. For the size fraction of 38~75 μm , all diffraction peaks at various planes of the three CuFeS_2 samples exhibited a similar intensity, suggesting that the exposed percentages of each plane for the three smaller CuFeS_2 particles were similar (Figure 2a), since the intensity of the diffraction peak is highly related to the exposed percentage of the planes [27,33,36]. In contrast, the intensities of diffraction peaks at various planes for the three CuFeS_2 samples with a particle size of 75~150 μm were significantly different (Figure 2b), suggesting that bigger CuFeS_2 particles from all three grinding methods had different exposed percentages for each plane, thus presenting different leaching rules as shown in Figure 1b. In other words, the anisotropic crystal planes of the CuFeS_2 particles seemed to dominate their leaching behavior.

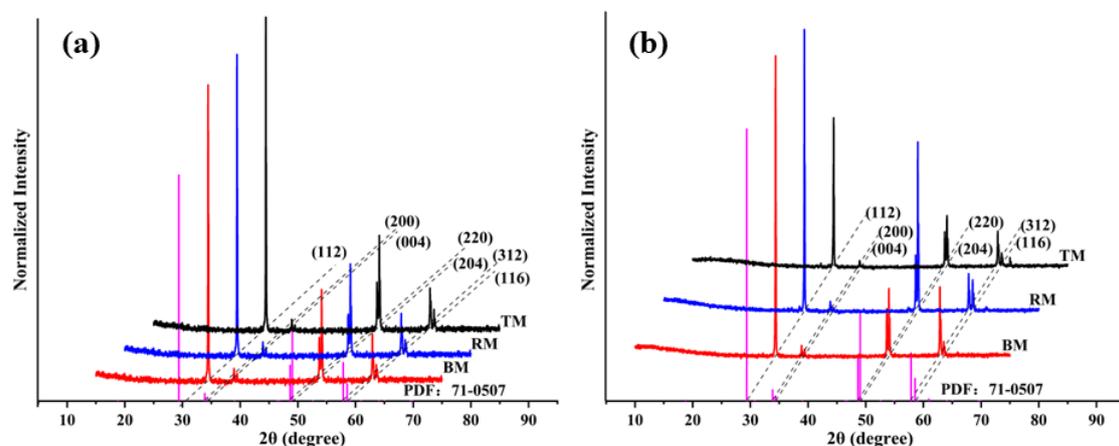


Figure 2. XRD patterns of raw CuFeS_2 samples obtained through three grinding methods: (a) 38~75 μm ; (b) 75~150 μm . PDF: 71-0507 was the standard XRD pattern of CuFeS_2 from Jade 6.0.

In order to further investigate the anisotropy of the raw CuFeS_2 samples, the normalized percentages of the typically exposed planes for three CuFeS_2 samples based on the diffraction peak intensity of each plane were calculated (Figure 3 and Tables S2 and S3). Obviously, the normalized percentage rules of the (112), (102), (312), (110), (116), (100), and (001) planes for the three CuFeS_2 samples with particle sizes of 38~75 μm and 75~150 μm were different, e.g., the differences in the normalized percentages between the standard value and the experimental value of the (112) plane for the TM, RM, and BM methods were -9.279% , -8.210% , and -7.456% for the three smaller CuFeS_2 particles, while they were -15.357% , -13.541% , and -6.307% for the three bigger CuFeS_2 particles, respectively, indicating that the three bigger CuFeS_2 particles exhibited greater differences in their exposure percentages. For the (001) plane, the three smaller CuFeS_2 samples still exhibited similarly normalized percentages for the TM, RM, and BM methods (i.e., 3.856%, 3.908%, and 3.264%, respectively). However, the three bigger CuFeS_2 particles exhibited different normalized percentages of the exposed planes for the TM, RM, and BM methods (i.e., 3.613%, 2.959%, and 2.053%, respectively), suggesting that the three bigger CuFeS_2 particles exhibited greater anisotropy than the smaller CuFeS_2 particles. In addition, the total percentages of the (112), (102), and (312) planes for the three bigger CuFeS_2 particles were in the order of $\text{TM} > \text{RM} > \text{BM}$, while the (110), (116), (100), and (001) planes exhibited a total percentage order of $\text{TM} < \text{RM} < \text{BM}$ (Figure 3), further demonstrating the crystal plane anisotropy for the three bigger CuFeS_2 particles.

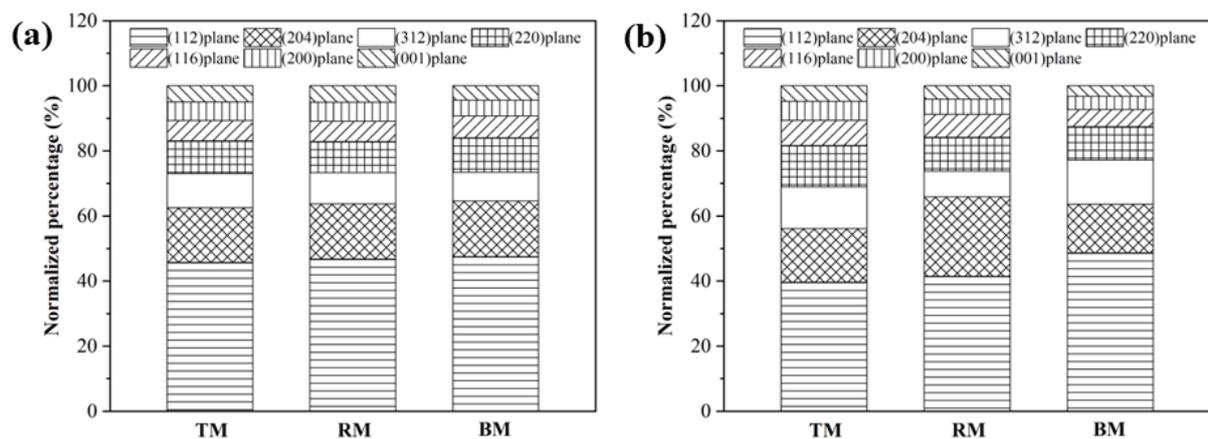


Figure 3. Normalized percentage of planes for three CuFeS_2 samples (%): (a) 38~75 μm ; (b) 75~150 μm .

Figure 4 presents the SEM results of raw CuFeS_2 samples at 75~150 μm for the TM, RM, and BM methods. It can be clearly observed that the samples in the TM and RM methods were mainly long, irregular particles, while the samples in the BM method were mainly rounded particles. As shown in Table 1, the length–width ratios based on the average length and width for raw CuFeS_2 samples in the TM, RM, and BM methods were 1.776, 1.759, and 1.299, respectively, suggesting that the exposure percentage for each plane was related to the length–width ratio of the particles. Combining the normalized percentage of the typical exposed plane and the length–width ratio of the raw CuFeS_2 samples, the long, irregular particles in the TM method exposed fewer (112), (102), (312), and (110) planes but more (116), (100), and (001) planes than the rounded particles in the BM method.

Table 1. Average length, width, and length–width ratio for three raw CuFeS_2 samples.

Grinding Methods	Average Length (μm)	Average Width (μm)	Length–Width Ratio
TM	127.762	71.953	1.776
RM	124.724	70.917	1.759
BM	95.234	73.276	1.299

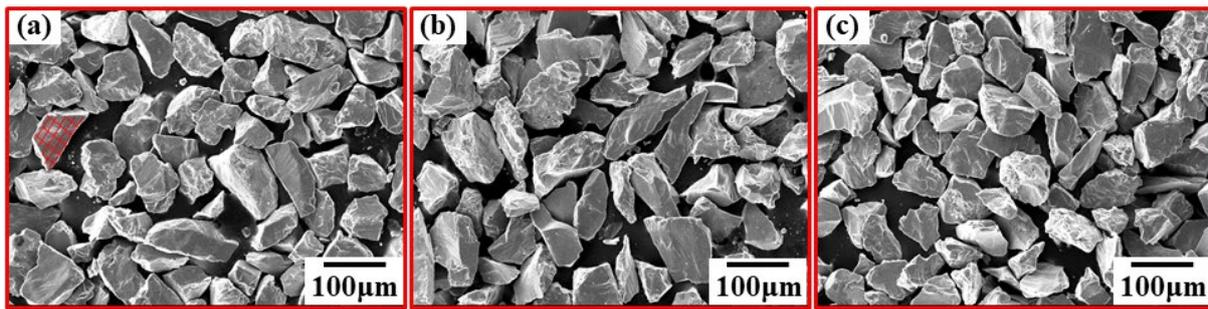


Figure 4. SEM images of raw CuFeS_2 samples (75~150 μm) obtained through three grinding methods: (a) TM; (b) RM; (c) BM. The average length and width of each raw CuFeS_2 sample was calculated based on 5 lengths and 5 widths as shown in (a) (the red lines), respectively.

3.3. XPS Analysis

The three bigger CuFeS_2 samples were tested using XPS to investigate the species differences on the CuFeS_2 surface. Figure 5 and Table 2 show the XPS survey spectra of the CuFeS_2 surface and the elemental quantification (at %) of the CuFeS_2 surfaces, respectively. The O 1s peak at 532.1 eV was found on the CuFeS_2 surface, and the O contents were 43.87%, 53.37%, and 70.40% on the surface of CuFeS_2 treated using the BM, RM, and TM methods, respectively, indicating that the order of the oxidation degree of the CuFeS_2 surface treated using different methods was $\text{TM} > \text{RM} > \text{BM}$.

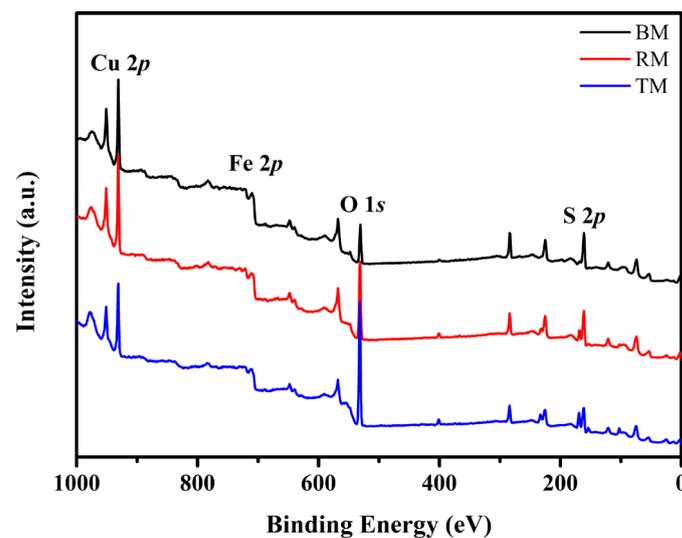


Figure 5. XPS survey spectra of CuFeS_2 treated using BM, RM, and TM.

Table 2. Elemental quantification (at %) of CuFeS_2 surface.

Element	Bonding Energy (eV)	CuFeS_2		
		BM	RM	TM
S 2p	161.4	9.26	4.93	8.08
O 1s	532.1	43.87	53.37	70.40
Fe 2p	710.8	8.56	9.48	4.88
Cu 2p	932.6	38.31	32.22	16.64

The Fe contents on the surface of CuFeS_2 treated using the BM, RM, and TM methods were determined to be 8.56%, 9.48%, and 4.88%, respectively, indicating that Fe was more readily leached from the surface of CuFeS_2 when treated with the TM method. The Cu contents on the surface of the CuFeS_2 treated using the BM, RM, and TM methods were

found to be 38.31%, 32.22%, and 16.64%, respectively, suggesting that Cu was more easily leached from the surface of CuFeS₂ when subjected to the TM method, compared with both the BM and RM methods. This observation is consistent with the leaching results presented in Figure 5.

Figure 6 and Table 3 show the fitted S 2*p* spectra and S species of the bigger CuFeS₂ particles treated using the BM, RM, and TM methods. The S 2*p*_{3/2} component located at 161.4 eV for CuFeS₂ was attributed to the monosulfide S^{2−} species [37,38]. The 2*p*_{3/2} spectra due to S₂^{2−}, S_n^{2−}, S⁰, SO₃^{2−}, SO₄^{2−} and the energy loss of CuFeS₂ were located at 162.2, 163.2, 163.7, 166.3, 168.8, and 165.1 eV, respectively [38–40]. The concentrations of S₂^{2−}, S_n^{2−}, S⁰, SO₃^{2−}, and SO₄^{2−} on the BM-treated CuFeS₂ surface were 8.60%, 0%, 23.57%, 3.81%, and 34.59%, respectively (Table 3). The presence of oxidized S species indicated that the surface S^{2−} of CuFeS₂ was oxidized to S₂^{2−}, S_n^{2−}, and S⁰, which were the main substances forming the passivation layer [41]. The passivation layer composed of S₂^{2−}, S_n^{2−}, and especially S⁰, hindered the further leaching of CuFeS₂, which was the main reason for the low leaching rate of CuFeS₂ treated using the BM method.

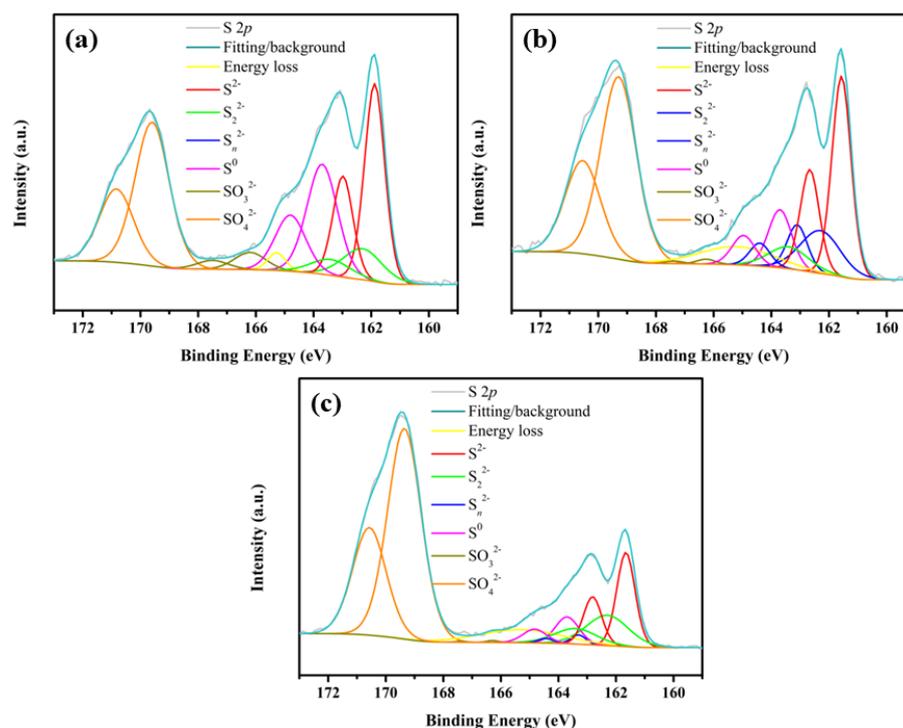


Figure 6. S 2*p* XPS spectra of CuFeS₂ treated using the (a) BM, (b) RM, and (c) TM methods.

Table 3. S species (at %) on CuFeS₂ surfaces treated under different conditions.

S Species	Bonding Energy (eV)	Full Width at Half-Maximum (eV)	CuFeS ₂		
			BM	RM	TM
S ^{2−}	161.4	0.7–0.8	27.98	23.01	14.87
S ₂ ^{2−}	162.2	0.7–0.9	8.60	10.32	11.07
S _n ^{2−}	163.2	1.1–1.3	0	5.50	1.19
S ⁰	163.7	1.0–1.2	23.57	8.12	5.44
SO ₃ ^{2−}	166.3	1.1–1.3	3.81	0.54	0.20
SO ₄ ^{2−}	168.8	1.5–1.6	34.59	39.02	61.14
Energy loss	165.1	1.4–1.7	1.46	5.37	6.10

The concentrations of S₂^{2−}, S_n^{2−}, S⁰, SO₃^{2−}, and SO₄^{2−} on the RM-treated CuFeS₂ surface were 10.32%, 5.50%, 8.12%, 0.54%, and 39.02%, respectively (Table 3). The S species

content on the surface of CuFeS₂ treated using the TM method was comparable to that observed on the surface of CuFeS₂ treated using the RM method, except for a higher presence of SO₄²⁻ compounds. The low concentration of S⁰ and the high concentration of SO₄²⁻ indicated that the surface of CuFeS₂ treated using the RM and TM methods had reduced passivation layer formation, enhancing the generation of highly oxidized SO₄²⁻ during leaching, further facilitating the leaching process. The highest SO₄²⁻ content was found on the CuFeS₂ surface treated using the TM method, indicating a significant oxidation reaction and the maximum leaching rate. Overall, the CuFeS₂ samples treated using the BM, RM, and TM methods in the same leaching conditions underwent varying degrees of oxidation, especially showing different evolutions for the S species on the chalcopyrite surface. These results indicate that the anisotropic crystal planes of CuFeS₂ significantly affected its leaching behavior.

3.4. The Properties of Anisotropic Crystal Planes

In order to further investigate the reactivities of CuFeS₂ planes, the properties of the CuFeS₂ planes were investigated through the same calculation methods as in our previous research (e.g., only Fe and S sites were considered for the adsorption of O₂) [27]. Due to the symmetry of the CuFeS₂ structure (i.e., each Cu/Fe atom is bonded with four surrounding S atoms, each S atom is bonded with two surrounding Cu atoms and two surrounding Fe atoms) [31], the CuFeS₂ (112), (312), (116), (100), and (001) planes exposed both sulfur-terminated (only exposing S atoms) and metal-terminated (only exposing Fe/Cu atoms) planes, while the CuFeS₂ (102) and (110) planes exposed mixed terminated (exposing both S and Fe/Cu atoms) planes during the cleavage process (Figure S2), which fully exhibited the anisotropic structure of CuFeS₂ planes.

Table 4 exhibits the surface energies of the CuFeS₂ planes, giving the order of (112)-S < (112)-M < (102) < (312)-M < (312)-S < (110) < (116)-S < (116)-M < (100)-S < (100)-M < (001)-S < (001)-M planes, suggesting that the stabilities of the CuFeS₂ planes were in the order of (112) > (102) > (312) > (110) > (116) > (100) > (001) planes [27,42–44], consistent with the exposed percentage of CuFeS₂ planes for all the grinding methods (Figure 3), e.g., the CuFeS₂ (112) plane obtained the lowest surface energy (0.923 J·m⁻² for the (112)-S plane and 1.018 J·m⁻² for the (112)-M plane) and was, thus, preferentially exposed during the grinding process [27], occupying the highest exposed percentage (more than 40%, Table S1). It should be noted that the CuFeS₂ (001) planes with the highest surface energy (1.495 J·m⁻² for the (001)-S plane and 1.556 J·m⁻² for the (001)-M plane) were less easily exposed during the grinding process, occupying the lowest exposed percentage (less than 5%, Table S1).

Table 4. Area, surface energy, and adsorption energy per unit area of O₂ for CuFeS₂ planes.

Planes	Area (nm ²)	Surface Energy, E _s (J·m ⁻²)	Adsorption Site	Adsorption Energy per Unit Area (kJ·mol ⁻¹ ·nm ⁻²)
112-S	0.473	0.923 ^a	S1	−437.384
112-M	0.473	1.018 ^a	Fe1	−1316.631
102	0.774	1.128 ^a	Fe1	−1372.095
			S3	−470.755
312-M	1.874	1.207 ^a	Fe1	−1571.115
312-S	1.874	1.221	S2	−477.523
110	0.408	1.332	Fe3	−1633.777
			S1	−461.095
116-S	0.909	1.351	S2	−527.396
116-M	0.909	1.494	Fe2	−1654.440
100-S	0.545	1.450	S3	−588.869
100-M	0.545	1.498	Fe3	−1858.123
001-S	0.274	1.495 ^a	S2	−690.193
001-M	0.274	1.566 ^a	Fe	−2027.415

^a These data have been published in our previous research [27].

Since the leaching experiments were performed in a sulfuric acid solution at pH = 1, components such as H₂O, O₂, SO₄²⁻, and HSO₄⁻ that could react with the CuFeS₂ planes were present in the solution. Research indicated that O₂ was adsorbed on the CuFeS₂ planes prior to the adsorption of H₂O, SO₄²⁻, and HSO₄⁻ [27,34,35]. For example, de Lima et al. [34,45] reported that the adsorption energies were −142.12, −105.34, and 95.30 kJ·mol⁻¹ for SO₄²⁻, HSO₄⁻, and H₂O at Fe sites on the CuFeS₂ (001) plane. Wei et al. [27] reported that the adsorption energies of H₂O and O₂ at Fe sites on the CuFeS₂ (001) plane were −153.94 and −556.12 kJ·mol⁻¹, respectively. In addition, the reactivity of the Fe sites was stronger than that of the Cu sites on the CuFeS₂ metal-terminated planes [27]. In this case, only the adsorption of O₂ at Fe and S sites on the CuFeS₂ planes was considered to compare the reactivity of each plane, and the results are shown in Table 4 and Figures 7 and S3.

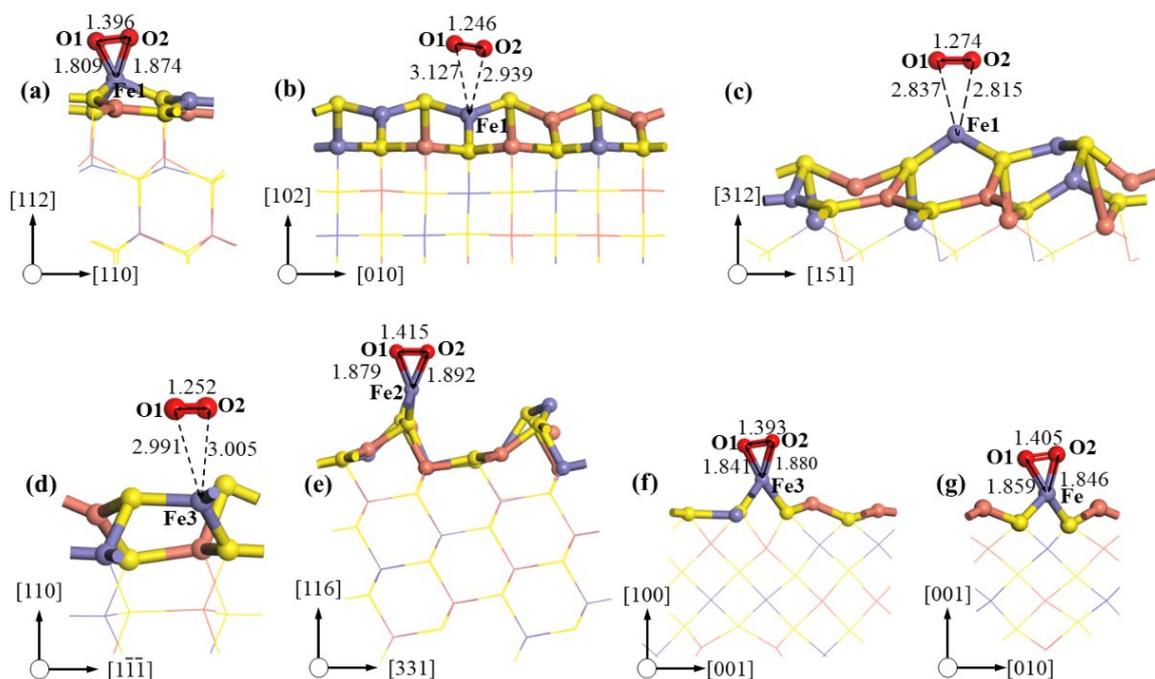


Figure 7. Layout of the adsorption of O₂ at Fe sites on CuFeS₂ planes: (a) (112)-M plane; (b) (102) plane; (c) (312)-M plane; (d) (110) plane; (e) (116)-M plane; (f) (100)-M plane; (g) (001)-M plane; distances are in Å.

It was clearly seen that the adsorption energy per unit area at Fe sites on each plane was more negative than that at S sites, suggesting that these Fe sites were more easily oxidized than the S sites due to the higher affinity of Fe sites for O₂ than that of S sites for O₂ [38]. For the adsorption of O₂ at Fe sites on CuFeS₂ planes, the adsorption energies per unit area were −1316.631, −1372.095, −1571.115, −1633.777, −1654.440, −1858.123, and −2027.415 kJ·mol⁻¹·nm⁻² for the (112)-M, (102), (312)-M, (110), (116)-M, (100)-M, and (001)-M planes, respectively, suggesting that the Fe site of the CuFeS₂ (001) plane was more easily oxidized by O₂ than that in other planes [27,46], thereby forming two Fe-O bonds with lengths of 1.846 Å and 1.859 Å (Figure 7g). The adsorption energy per unit area of O₂ at S sites on the CuFeS₂ planes exhibited the same rules as that at Fe sites. The adsorption energies per unit area for the (112)-S, (102), (312)-S, (110), (116)-S, (100)-S, and (001)-S planes were −437.384, −470.755, −477.523, −461.095, −527.396, −588.869, and −690.193 kJ·mol⁻¹·nm⁻², respectively, suggesting that both the Fe and S sites of the CuFeS₂ (001) plane were more easily oxidized by O₂; thus, the (001) plane was preferably leached compared with other planes. Overall, the leaching rates of the CuFeS₂ planes were in the order of (001) > (100) > (116) > (110) > (312) > (102) > (112) planes.

In addition, it was clearly seen that the adsorption energies per unit area at Fe sites on the (001)-M and (100)-M planes were more negative than those on other planes (Figure 8a), while those on the (001)-S, (100)-S, and (116)-S planes were significantly more negative than those on other planes at the S sites (Figure 8b). In this case, the CuFeS_2 samples that contained more (001), (100), and (116) planes, exhibited faster leaching rates, consistent with the leaching experiment results, in which the Cu extraction was in the order of $\text{TM} > \text{RM} > \text{BM}$ methods (Figure 1).

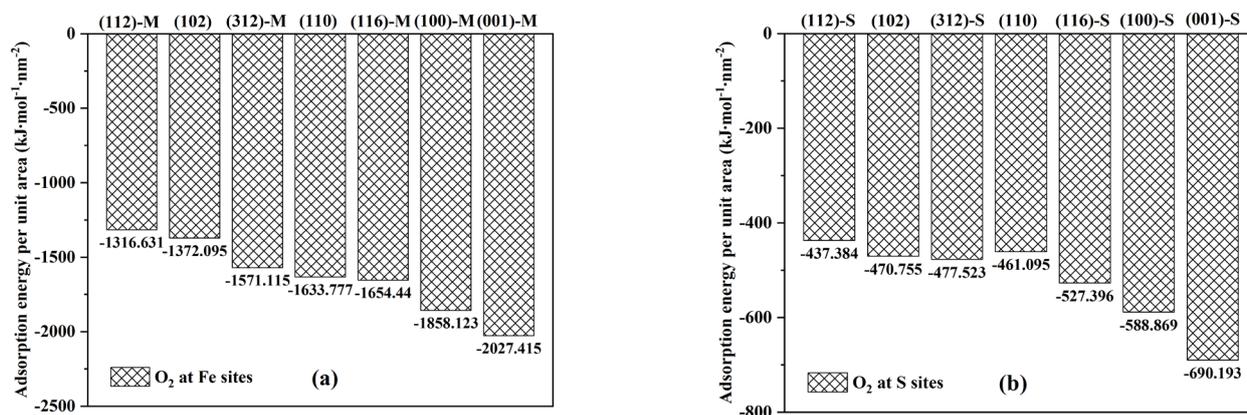


Figure 8. Adsorption energy per unit area for O_2 on CuFeS_2 planes: (a) Fe sites; (b) S sites.

4. Conclusions

In this work, a three-head laboratory mill with a grinder mill (TM), rod mill (RM), and ball mill (BM) was employed to obtain CuFeS_2 samples with anisotropic crystal planes. Interestingly, the trend of Cu extractions for three CuFeS_2 samples with a particle size of 38~75 μm increasing with leaching time were similar, while the Cu extractions were in the order of $\text{TM} > \text{RM} > \text{BM}$ methods for the three CuFeS_2 samples with a particle size of 75~150 μm , indicating that the anisotropic crystal planes of CuFeS_2 particles could significantly affect CuFeS_2 leaching behavior. The exposed percentages of the CuFeS_2 planes were in the order of (112) > (102) > (312) > (110) > (116) > (100) > (001) planes, and the long, irregular particles obtained using the TM method exposed fewer (112), (102), (312), and (110) planes and more (116), (100), and (001) planes. Since the adsorption of O_2 on CuFeS_2 planes indicated that the leaching rates were in the order of (001) > (100) > (116) > (110) > (312) > (102) > (112) planes, CuFeS_2 samples treated using the TM method exhibited the highest oxidization degree. The formation of more SO_4^{2-} species indicated that CuFeS_2 samples treated using the TM method had the least amount of passivation layer, thus exhibiting the highest leaching rate.

Supplementary Materials: The following are available online at <https://www.mdpi.com/article/10.3390/min13111461/s1>: Figure S1. XRD patterns of raw CuFeS_2 sample (D8 Advance, Bruker, Germany). PDF: 71-0507 was the standard XRD pattern of CuFeS_2 from Jade 6.0. It was clear that the diffraction peaks of the raw chalcopyrite sample were highly consistent with the standard CuFeS_2 XRD pattern (PDF: 71-0507), indicating that the raw CuFeS_2 sample in this study was highly purified. Figure S2. Structure and exposed atoms of CuFeS_2 planes. Figure S3. Layout of the adsorption of O_2 at S sites on the CuFeS_2 planes: (a) (112)-S plane; (b) (102) plane; (c) (312)-S plane; (d) (110) plane; (e) (116)-S plane; (f) (100)-S plane; (g) (001)-S plane; distances are in Å. Table S1. Main element contents of CuFeS_2 sample using XRF (Zetium, PANalytical, Almelo, Netherlands) (wt. %). Table S2. Normalized exposure percentage of planes for standard and experimental CuFeS_2 particles (%). Table S3. Relatively normalized exposed percentage of planes for CuFeS_2 particles between standard value and experimental value (%).

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